P. Schacht, 2.12.00.

Status at MPI: Report December 2000

Module Assembly

Status: presently 9 modules assembled

- CF19 and CR21 in june testbeam
- CF20 and CR18 in august testbeam
- CR19, CR26 (Cu from Molniya), CR17 (Cu from Protvino), CR20 (Cu from Protvino) in cold test november 2000
- CR25 (Cu from Molniya) finished, waiting for shipment to CERN

Problems: CR17, CR20, CR26 and CR25 had to partially re-assembled, because old (bad) EST electrodes had been used.....!

Actions in near future

- Cu-plates from 2 Rear Module 0's redone. one rear module stacking finished, cabling to be done in near future.
- Cu plates for CR15 and CR16 on the way from Protvino to Munich
  arrived now in Munich! BUT: problem with thickness of one plate!

Requests

- Cu plates for 2 front modules from Dubna (31.12.00)
- Padbords for 2 front modules from Mainz (15.2.01)

Cold Electronics

- GaAs chips: Done
- PSB Boards:

PSB	plan	needed	produced	functional test passed	Full QC done
1	75	64	75	69	56
2-1	75	64	75	73	28
2-2	75	64	75	73	28
3	75	64	75	70	27
4	75	64	75	73	27
Total	375	320	375 100%	358 95.5%	166 44.3%

Module Cabling

- Signal Cabling
  - Front Modules: 64 of 70 received (17 left in MPI) (6 ordered in addition later!)
  - Rear Modules: 64 of 64 received (6 left in Protvino) 6 ordered in addition later!
- HV Cabling:
  - Front Modules: 70 of 70 received (24 left in MPI)
  - Rear Modules: 70 of 70 received (43 left in MPI)
- HV Distribution Boards: 153 of 150 received (98 left in MPI)
- Calibration Distribution Boards:
  - Front Modules: 79 of 75 received (31 left in MPI)
  - Rear Modules: 77 of 75 received (63 left in MPI)

EST/PAD-Boards and Hexcel

	EST1	needed per module	EST2	needed per module
Family 1	28	8	29	8
Family 2	29	8	29	8
Family 3	29	8	29	8
Family 4	20	8	17	8
Family 5	24	8	24	8

	PAD	needed per module
Family 1	2	8
Family 2	1	8
Family 3	1	8
Family 4	25	4
Family 5	27	4
Family 6	26	4
Family 7	23	4

	Hexcel	needed per module
Family 1	220	32
Family 2	217	32
Family 3	212	32
Family 4	200	32
Family 5	204	32